

Wireless Modules for IoT Applications

BLE module

Type 1GR

PN: LBCA1CW1GR-084
CYW20736 Chipset



9.0 x 7.0 x 1.2 mm

- Software Option 1
- FCC/IC Certified

Bluetooth® 4.1

Wi-Fi® module

Type 1FX*†

PN: LBWA1KL1FX-875
CYW43364 Chipset



6.95 x 5.15 x 1.1 mm

- Software Option 1
- FCC/IC Reference Certified

802.11 b/g/n

Wi-Fi® + Bluetooth® modules

Type 1DX*†

PN: LBEE5KL1DX-883
CYW4343W Chipset



6.95 x 5.15 x 1.1 mm

- Software Option 1
- FCC/IC Reference Certified

802.11 b/g/n + Bluetooth® 4.1

Type 1BW

PN: LBEH5DU1BW-777
CYW43340 Chipset



8.0 x 7.5 x 1.13 mm

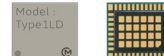
- Software Option 1

802.11 a/b/g/n + Bluetooth® 4.0

Wi-Fi® + Bluetooth® + MCU

Type 1LD

PN: LBEE5PA1LD-005
CYW43438 + STM Chipset



8.9 x 7.8 x 1.2 mm

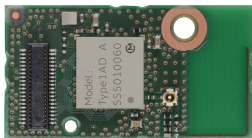
- Software Option 1
- ARM Cortex M4

802.11 b/g/n + Bluetooth® 4.1

Wi-Fi® + MCU

Type 1ADD*† Type 1AD†

PN:LBWB1ZZ1AD-812
PN:LBWA1CS1AD-806 (SIP)
CYW4390 Chipset



33.0 x 18.0 x 2.5 mm

- Software Option 2
- FCC/IC Certified
- ARM Cortex M3

802.11 b/g/n

Type 1CD

PN: LBWA1ZV1CD-716 (imp003)*
CYW43362+STM Chipset



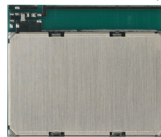
10.0 x 7.9 x 1.25 mm

- 1CD – Software Option 3
- FCC/IC Reference Certified
- ARM Cortex M4

802.11 b/g/n

Type 1HD/1MD†

PN: LBWA1ZZ1HD-004 (WICED)
PN: LBEE5ZZ1MD-011 (imp004m)*
CYW43438+STM Chipset



21.0 x 17.5 x 2.3 mm

- 1HD: Software Option 1
- 1MD: Software Option 3
- FCC/IC Certified
- ARM Cortex M4

802.11 b/g/n

Type 1GC†

PN: LBWA1UZ1GC-958 (WICED)
PN: LBWA1UZ1GC-901 (imp005)*
CYW43907 Chipset



10.0 x 10.0 x 1.2 mm

- Software Options 1, 3
- FCC/IC Reference Certified
- Ethernet
- ARM Cortex R4

802.11 a/b/g/n

*Modules available in Distribution Channels

☁ = Built-in Cloud Agent

†CE Marking Conformity Assessment Procedures are available



Software Solutions for IoT Applications

1. WICED* SDK by Cypress

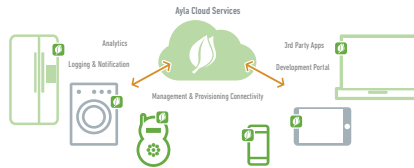


Allows custom solutions for various microcontrollers

*Wireless Internet Connectivity for Embedded Devices

2. Agile Enterprise IoT Platform by

Ayla Cloud Services



Ayla Embedded Agents
Ayla Application Libraries
Secure connectivity, application empowerment,
data intelligence, operational support

PN: LBWB1ZZYDZ-683
PN: LBWA1CS1AD-806
PN: LBWB1ZZ1AD-812

3. IoT Cloud Development by



Fast IoT Development

Connect to any Web service

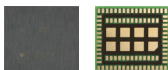
PN: LBWA1ZV1CD-716 (imp003)
PN: LBEE1ZZ1MD-011 (imp004m)
PN: LBWA1UZ1GC-901 (imp005)

Wi-Fi®/Bluetooth® Modules with TI

WiLink 8

Type WM

PN: LBEP5CLWMC-603 (802.11 a/b/g/n)
PN: LBEP5CLWMC-633 (802.11 a/b/g/n + Bluetooth® 4.1)
WL1803/1833 Chipset

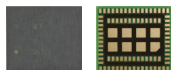


9.9 x 8.8 x 1.3 mm

 **802.11 a/b/g/n**
(633 includes Bluetooth® 4.1)

Type WT

PN: LBEP5CLWTC-601 (802.11 b/g/n)
PN: LBEP5CLWTC-631 (802.11 b/g/n + Bluetooth® 4.1)
WL1801/1831 Chipset

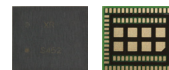


9.9 x 8.8 x 1.3 mm



 **802.11 b/g/n**
(631 includes Bluetooth® 4.1)

Type XR

PN: LBEP5CLXRC-701 (802.11 b/g/n)
WL1801 Chipset



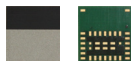
9.9 x 8.8 x 1.3 mm

 **802.11 b/g/n**
Supports industrial operating temp: -40°C to +85°C 

SimpleLink

Type 1ME

PN: LBCA1HN1ME-TEMP
CC2640 BLE Chipset



7.4 x 7.0 x 1.35 mm

 **Bluetooth® 4.2**

Type 1JP/1JQ

PN: LBWA1ZZ1JP-928 (without Host MCU)
PN: LBWA1ZZ1JQ-171 (with Host MCU)
CC3100/CC3200 Chipset



13.2 x 21.45 x 2.65 mm

● FCC/IC Certified

 **802.11 b/g/n + ARM Cortex M4**

Type 1KS

PN: LBWA1ZZ1KS-088
CC3220SF Chipset



13.2 x 21.45 x 2.65 mm

● Secure element

 **802.11 b/g/n + ARM Cortex M4**

